

Attorney's Docket No. 05542-459001 / 5353/CMP

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Wallace T.Y. Tang  
Serial No. : 07/996,817  
Filed : December 28, 1992  
Title : IN-SITU REAL-TIME MONITORING TECHNIQUE AND APPARATUS FOR  
ENDPOINT DETECTION OF THIN FILMS DURING  
CHEMICAL/MECHANICAL POLISHING PLANARIZATION

Art Unit : 1763  
Examiner : Thi Dang  
Confirmation No.: 2081  
Notice of Allowance Date: August 6, 2002

**BOX ISSUE FEE**

Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT UNDER 37 CFR 1.312

Please amend the application as issued below. This amendment is being filed concurrently with the payment of the issue fee.

In the Claims:

Please amend claims 59, 62, 68 and 82 as follows:

-- 59. (Amended) A method for producing a semiconductor device or a patterned layer intermediate, which comprises the steps of:

chemically mechanically polishing at least one layer on one side of the semiconductor device or patterned layer intermediate, wherein the layer is composed of a material selected from the group consisting of an insulating material, a semi-conducting material, a conducting material, and combinations thereof,

illuminating the side of the semiconductor device or patterned layer intermediate not being polished with light of a wavelength between about 1,000 nm and about 11,000

## CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

November 6, 2002

Date of Deposit

Signature

Jennifer Leveill

Typed or Printed Name of Person Signing Certificate